4 Appl. No. 09/891,316 Reply to Final OA dated May 6, 2003 "RESPONSE UNDER 37 CFR 1.116-EXPEDITED PROCEDURE EXAMINING GROUP 2611 "

DOCKET NO: 210093US2S

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

SHOTARO UCHIDA

: EXAMINER: IM, J.

SERIAL NO: 09/891,316

FILED: JUNE 27, 2001

: GROUP ART UNIT: 2811

FOR: SEMICONDUCTOR DEVICE MANUFACTURING METHOD AND SEMICONDUCTOR DEVICE MANUFACTURED THEREBY

AMENDMENT UNDER 37 C.F.R. § 1.116

COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313

SIR:

In response to the Office Action of May 6, 2003, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend Claims 21 and 24 as follows:

21. (Amended) A semiconductor device comprising:

a transistor chip having a first main electrode and a gate electrode for a transistor on an upper surface of the transistor chip, a second main electrode on a bottom surface of the transistor chip, and a Schottky diode connected in parallel to the transistor;

a package base to which the second main electrode of the transistor chip is joined and connected;

